

Packing Tool mPT 200/300



Applications

- packing
- unpacking

Features

- optimized footprint
- high throughput
- handling of wafer
- Cleanroom class: ISO class 6
- CE certificated
- SEMI standards compliant

Basic Configuration

- two 6-axis robots
- Bernoulli vacuum end-effectors 8" and 12"
- two load-ports for 8" and 12"
- four stations for shipping boxes
- four stations for packing material
- GUI/Operator interface

Description

The Packing Tool mPT200/300 is designed for packing and unpacking of 200/300 mm (8"/12") wafers by using bernoulli vacuum end-effectors.

Configuration Options

- OCR reader for wafer ID
- RFID antennas
- End-effector change station
- SECS/GEM interface
- FFU (fan filter unit) for higher cleanroom class
- Ionizer

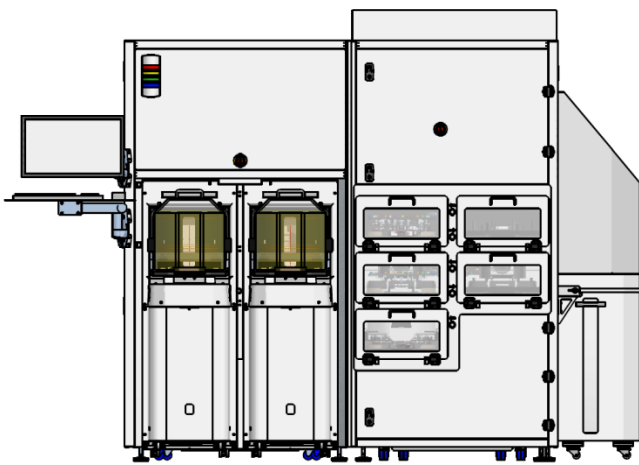
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Packing Tool

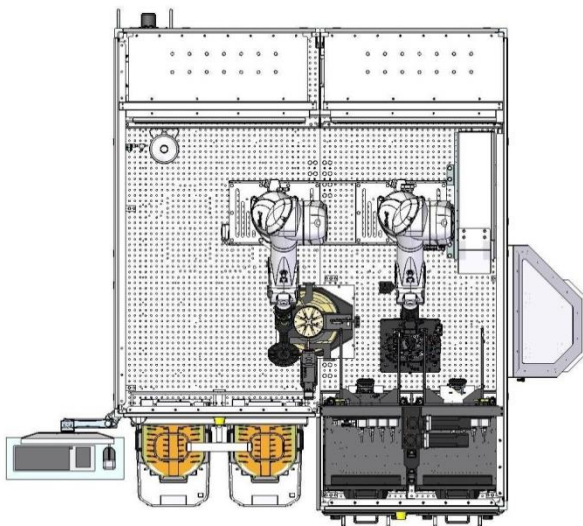
mPT 200/300

Specifications

Front view



Plan view



Wafer size	200 mm (8") and 300 mm (12")
Cleanroom class*	ISO class 6
Dimensions	
w / d / h in mm	1970 / 2662 / 2150
Service area	600 mm around the machine
Weight	About 2400 kg
Operation and loading	
Operation and loading	Front
Carrier loading	Manual
Shipping box and packing material loading	Manual
Supply	
Power supply	400 VAC / 50-60 Hz 3+N
Control voltage	24 VDC
Pneumatic	
Pneumatic media	CDA and Vacuum
Supply pressure CDA	6.0 – 7.0 bar
Supply pressure Vacuum	-75 to -85 kPa
Interface	
Operator interface	Monitor + keyboard (opt. touch screen)
External interface	USB, Ethernet, SECS/GEM (optional)
Service Interface	Remote control (optional)
Throughput	
Throughput (depends on recipe)	Depends on recipe
CE certificates	2006/95/EC, 2006/42/EC, 2004/108/EC
SEMI standards compliant	

* ISO EN 14 644-1

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